

isola

G200

Epoxy Laminate and Prepreg

Isola's G200 product is a fully proven laminate and prepreg system designed to meet today's high reliability printed circuit board requirements.

Blending Bismaleimide/Triazine (BT) and epoxy resin provides G200 with enhanced thermal, mechanical and electrical performance over most epoxy materials. G200 possesses performance characteristics that make it an excellent selection for large panel size, high layer count Printed Wiring Boards (PWB).

Product Attributes

Legacy Materials

Typical Market Applications

Aerospace & Defense

Legacy Materials

Data Sheet

Tg 180°C

Td 325°C

Dk 3.70

Df 0.013

IPC-4101/30

UL - File Number E41625

Last Updated December 7, 2017
Revision No: 8

Product Features

Product Availability

Property	Typical Value	Units	Test Method
		Metric (English)	IPC-TM-650 (or as noted)
Glass Transition Temperature (Tg) by DSC	180	°C	2.4.25C
Decomposition Temperature (Td) by TGA @ 5% weight loss	325	°C	2.4.24.6
Time to Delaminate by TMA (Copper removed)	A. T260 B. T288	60 >10	Minutes 2.4.24.1
Z-Axis CTE	A. Pre-Tg B. Post-Tg C. 50 to 260°C, (Total Expansion)	55 275 3.30	ppm/°C ppm/°C % 2.4.24C
X/Y-Axis CTE	Pre-Tg	13/14	ppm/°C 2.4.24C
Thermal Conductivity		0.35	W/mK ASTM E1952
Thermal Stress 10 sec @ 288°C (550.4°F)	A. Unetched B. Etched	Pass	Pass Visual 2.4.13.1
Dk, Permittivity	A. @ 100 MHz B. @ 1 GHz C. @ 2 GHz D. @ 5 GHz E. @ 10 GHz	3.80 3.70 3.70 3.65 3.65	— 2.5.5.3 2.5.5.9 Bereskin Stripline Bereskin Stripline Bereskin Stripline
Df, Loss Tangent	A. @ 100 MHz B. @ 1 GHz C. @ 2 GHz D. @ 5 GHz E. @ 10 GHz	0.0150 0.0150 0.0130 0.0150 0.0150	— 2.5.5.3 2.5.5.9 Bereskin Stripline Bereskin Stripline Bereskin Stripline
Volume Resistivity	A. After moisture resistance B. At elevated temperature	8.9 x 10 ⁸ 6.5 x 10 ⁸	MΩ-cm 2.5.17.1
Surface Resistivity	A. After moisture resistance B. At elevated temperature	2.21 x 10 ⁶ 4.4 x 10 ⁸	MΩ 2.5.17.1
Dielectric Breakdown		>60	kV 2.5.6B
Arc Resistance		130	Seconds 2.5.1B
Electric Strength (Laminate & laminated prepreg)		45 (1175)	kV/mm (V/mil) 2.5.6.2A
Comparative Tracking Index (CTI)		3 (175-249)	Class (Volts) UL 746A ASTM D3638
Peel Strength	A. Low profile copper foil and very low profile copper foil all copper foil >17 µm [0.669 mil] B. Standard profile copper 1. After thermal stress 2. After process solutions	1.14 (6.5) 0.96 (5.5) 0.90 (5.1)	N/mm (lb/inch) 2.4.8C 2.4.8.2A 2.4.8.3
Flexural Strength	A. Length direction B. Cross direction	86,900 73,600	ksi 2.4.4B
Tensile Strength	A. Length direction B. Cross direction	51,551 42,436	ksi ASTM D3039
Young's Modulus	A. Length direction B. Cross direction	3489 3200	ksi ASTM D790-15e2
Poisson's Ratio	A. Length direction B. Cross direction	0.182 0.160	— ASTM D3039
Moisture Absorption		0.2	% 2.6.2.1A
Flammability (Laminate & laminated prepreg)		V-0	Rating UL 94
Max Operating Temperature		130	°C UL 796

The data, while believed to be accurate and based on analytical methods considered to be reliable, is for information purposes only. Any sales of these products will be governed by the terms and conditions of the agreement under which they are sold.

